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Field Device Integration (FDI) - Part 101-2: Profiles - Foundation Fieldbus HSE

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 07/23

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Supersedes EN IEC 62769-101-2:2021

English Version

**Field Device Integration (FDI)® - Part 101-2: Profiles -
Foundation Fieldbus HSE
(IEC 62769-101-2:2023)**

Intégration des appareils de terrain (FDI)® - Partie 101-2:
Profils - Foundation Fieldbus HSE
(IEC 62769-101-2:2023)

Feldgeräteintegration (FDI)® - Teil 101-2: Profile -
Foundation Fieldbus HSE
(IEC 62769-101-2:2023)

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EN IEC 62769-101-2:2023 (E)**European foreword**

The text of document 65E/861/CDV, future edition 3 of IEC 62769-101-2, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-101-2:2023.

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

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NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61784-1	-	Industrial communication networks - Profiles Part 1: Fieldbus profiles	EN IEC 61784-1	-
IEC 61784-2	-	Industrial communication networks - Profiles - Part 2: Additional fieldbus profiles for real- time networks based on ISO/IEC/IEEE 8802-3	EN IEC 61784-2	-
IEC 61804	series	Function blocks (FB) for process control and electronic device description language (EDDL)	EN IEC 61804	series
IEC 62541-6	-	OPC Unified Architecture - Part 6: Mappings	EN IEC 62541-6	-
IEC 62541-100	-	OPC Unified Architecture - Part 100: Device Interface	EN 62541-100	-
IEC 62769-2	-	Field Device Integration (FDI®) - Part 2: Client	EN IEC 62769-2	-
IEC 62769-3	-	Field Device Integration (FDI®) - Part 3: Server	EN IEC 62769-3	-
IEC 62769-4	-	Field Device Integration (FDI®) - Part 4: FDI Packages	-	-
IEC 62769-5	-	Field Device Integration (FDI®) - Part 5: FDI Information Model	-	-
IEC 62769-6	-	Field Device Integration (FDI®) - Part 6: FDI Technology Mappings	EN IEC 62769-6	-
IEC 62769-7	-	Field Device Integration (FDI®) - Part 7: Communication Devices	-	-
IEC 62769-101-1	-	Field device Integration (FDI®) - Part 101-1: Profiles - Foundation Fieldbus H1	-	-



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INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Field Device Integration (FDI)[®] –
Part 101-2: Profiles – Foundation Fieldbus HSE**

**Intégration des appareils de terrain (FDI)[®] –
Partie 101-2: Profils – Foundation Fieldbus HSE**



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IEC 62769-101-2

Edition 3.0 2023-04

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Field Device Integration (FDI)[®] –
Part 101-2: Profiles – Foundation Fieldbus HSE**

**Intégration des appareils de terrain (FDI)[®] –
Partie 101-2: Profils – Foundation Fieldbus HSE**

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IEC 62769-101-2 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2020. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added namespace to Annex A;
- b) changed content type of cff file to application/vnd.ff.cff.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/861/CDV	65E/918/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

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FIELD DEVICE INTEGRATION (FDI®) –

Part 101-2: Profiles – Foundation Fieldbus HSE

1 Scope

This part of IEC 62769 specifies the IEC 62769 profile for IEC 61784-1, CP 1/2 (FOUNDATION™ Fieldbus HSE)¹.

2 Normative references

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IEC 61804 (all parts), *Devices and integration in enterprise systems – Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

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